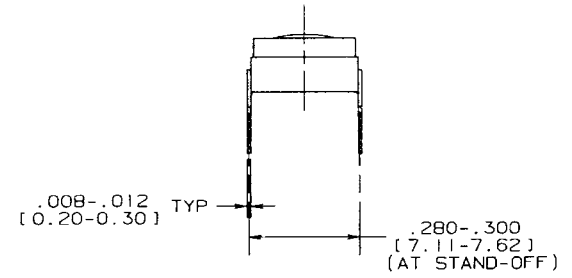
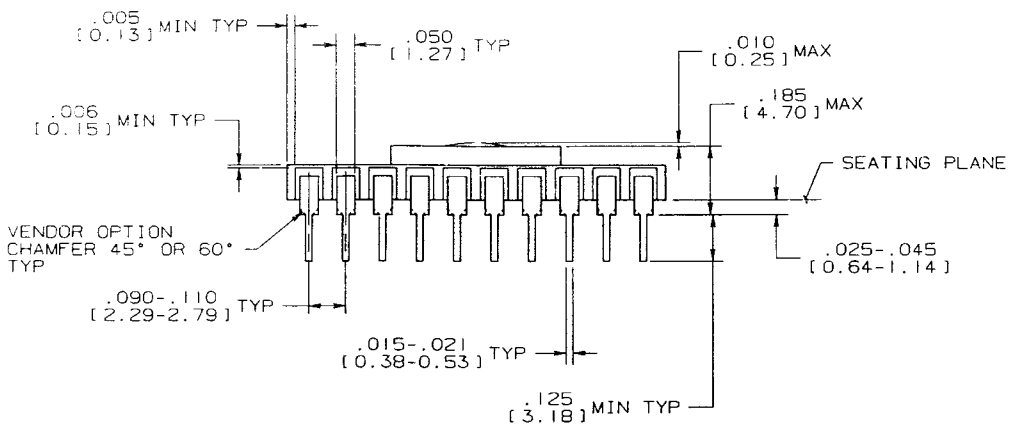
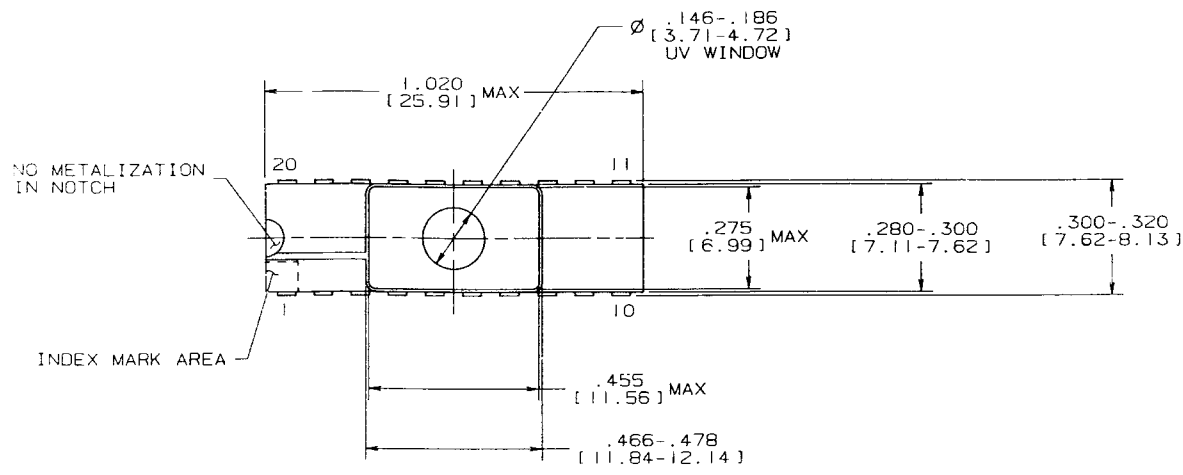


REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
A	RELEASE TO DOCUMENT CONTROL	08263	11/26/90



NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - a) 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - b) 200 TO 800 MICROINCHES/5.08 TO 20.32 MICROMETERS TIN PLATE OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE OR BASIS METAL.
 - c) 50 TO 100 MICROINCHES/1.27 TO 2.54 MICROMETERS GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
2. LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.

CONTROLLING DIMENSION: INCH			
DATE	11/26/90	NATIONAL SEMICONDUCTOR CORPORATION	
DRAWN	PAMELA GIFFORD	2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DFTG. CHK.	Shirley Duley	HERMETIC DIP(D), 20 LEAD, EPROM	
ENGR. CHK.	Alfred Lee		
APPROVAL		SCALE	N/A
PROJECTION		SIZE	C
		DRAWING NUMBER	MKT-D20CQ
		REV	A
		FORMERLY:	N/A
		SHEET	1 OF 1